

[ABSTRACT OF THE DISCLOSURE]

The present invention provides a film for a spacer applied to a multi-chip package and a method of forming a spacer using the same. The film for a spacer according to the present invention includes a first film; and an adhesive layer disposed on a lower portion of the first film, wherein an amount of curl, which is measured by cutting a portion where the first film and the adhesive layer are stacked into a rectangle with a width of 50 mm and a length of 15 mm, and placing the cut portion on a horizontal surface so that the adhesive layer faces downward, is 5 mm to 20 mm.

Figure 5

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